2020 Edition

Innodisk Selection Guide

Flash Storage, DRAM Modules, Embedded Peripherals, and Software Solutions
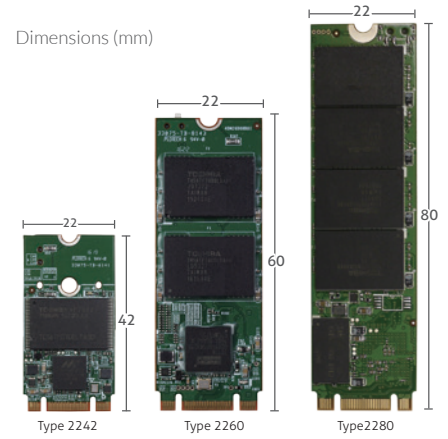
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M.2

The Innodisk M.2 series pack a lot of performance into a thin, industrial grade form factor. The M.2 series includes both Non-Volatile Memory Express (NVMe) and SATA devices. The NVMe specification is designed specifically for flash devices and can deliver the fastest speeds in the industry.

M.2 (NVMe) Highlights

Dimensions (mm)

- PCIe Gen 3×2 and 3×4 solution
- Truly industrial-grade PCIe NVMe SSD
- Heatsink-less design
- Wide range of form factors and dimensions available, including type 2242, 2260, and 2280
- Supports industrial-grade wide temperature -40℃~85℃
- iData Guard, iPower Guard, and iCell technology for data protection and integrity during abnormal power failure
- Supports iSMART™ disk health monitoring
- Supports end-to-end data path protection (ETEP)

Type 2242   Type 2260   Type2280

Model Name	M.2 (P42) 3ME2	M.2 (P42) 3TE2	M.2 (P42) 3TE6	M.2 (P80) 3ME2	M.2 (P80) 3TE2
Key Features	1. Low power consumption 2. Less controller heat 3. Supports NVMe 1.2 4. End-to-end data path protection 5. iData Guard data protection	1. Low power consumption 2. Less controller heat 3. Supports NVMe 1.2 4. End-to-end data path protection 5. iData Guard data protection	1. DRAM-less solution 2. Supports NVMe 1.3 3. iData Guard data protection 4. End-to-end data path protection 5. HMB feature 6. AES encryption	1. Low power consumption 2. Less controller heat 3. Supports NVMe 1.2 4. End-to-end data path protection 5. iData Guard data protection	1. Low power consumption 2. Less controller heat 3. Supports NVMe 1.2 4. End-to-end data path protectio 5. iData Guard data protection
Interface	PCIe Gen3x2	PCIe Gen3x2	PCIe Gen3×4	PCIe Gen3x2	PCIe Gen3x2
Flash Type	MLC	3D TLC	3D TLC	MLC	3D TLC
Capacity	32GB~256GB	64GB~512GB	64GB~1TB	32GB~512GB	64GB~1TB
Max. Channel	4	4	4	4	4
Sequential R/W (MB/sec, max.)	1300/340	1400/700	2000/1200	1300/480	1400/700
Max. Power Consumption	2.9W (3.3 x 880mA)	2.3W (3.3 x 700mA)	TBD	3.72W (3.3 x 1125mA)	3W (3.3 x 910mA)
Thermal Sensor	Y	Y	Y	Y	Y
External DRAM Buffer	N	N	N	N	N
iData Guard	Y	Y	Y	Y	Y
iCell	N	N	N	Optional	Optional
TRIM	Y	Y	Y	Y	Y
ATA Security	N	N	N	N	N
S.M.A.R.T	Y	Y	Y	Y	Y
Dimension (WxLxH/mm)	22.0 x 42.0 x 3.5	22.0 x 42.0 x 3.5	22.0 x 42.0.0 x 3.5	22.0 x 80.0 x 3.5	22.0 x 80.0 x 3.5
Environment	Shock: 1500G@0.5ms/Storage Temperature: -55℃ ~ +95℃/MTBF: >3 million hours				
Standard Temp. OP (0℃~+70℃)	DEM24-XXXM61BC***	DEM24-XXXM61EC***	DEM24-XXXDD1EC***	DEM28-XXXM61BC***	DEM28-XXXM61EC***
Wide Temp. OP (-40℃~+85℃)	DEM24-XXXM61BW***	DEM24-XXXM61EW***	DEM24-XXXDD1EW***	DEM28-XXXM61BW***	DEM28-XXXM61EW***
Note	XXX = density (02GB=02G, 04GB=04G, 08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G, 128GB=A28, 256GB=B56, 512GB=C12, 1TB=01T, 2TB=02T)***= flash configuration (internal control code) %=Flash Type				

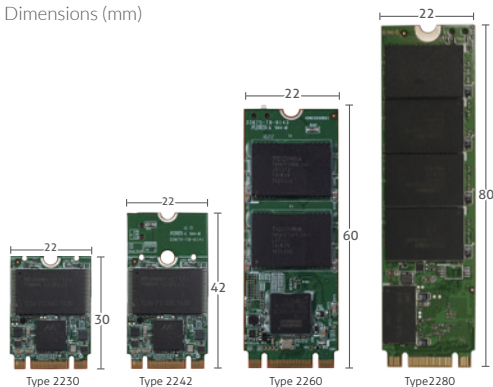| Model Name	M.2 (P80) 3TE6	M.2 (P80) 3TG3-P
Key Features	1. Type-2280-S2-M 2. DRAM-less solution 3. Supports NVMe 1.3 4. iData Guard data protection 5. End-to-end data path protection 6. HMB feature 7. AES encryption	1. Type-2280-D2-M 2. Ultra-high performance 3. Supports NVMe 1.3 4. iData Guard data protection 5. End-to-end data path protection
Interface	PCIe Gen3×4	PCIe Gen3x4
Flash Type	3D TLC	3D TLC
Capacity	64GB~2TB	128GB~2TB
Max. Channel	4	8
Sequential R/W (MB/sec, max.)	2000/1500	3400/2800
Max. Power Consumption	TBD	6.27W (3.3 x 1900mA)
Thermal Sensor	Y	Y
External DRAM Buffer	N	Y
iData Guard	Y	Y
iCell	N	N
TRIM	Y	Y
ATA Security	N	N
S.M.A.R.T	Y	Y
Dimension (WxLxH/mm)	22.0 x 80.0 x 3.5	22.0 x 80.0 x 3.5
Environment	Shock: 1500G@0.5ms/Storage Temperature: -55℃ ~ +95℃/MTBF: >3 million hours	
Standard Temp. OP (0℃~+70℃)	DEM28-XXXDD1EC***	DGM28-XXXDA1EC***
Wide Temp. OP (-40℃~+85℃)	DEM28-XXXDD1EW***	TBD
Note	XXX = density (02GB=02G, 04GB=04G, 08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G, 128GB=A28, 256GB=B56, 512GB=C12, 1TB=01T, 2TB=02T)***= flash configuration (internal control code) %=Flash Type	

M.2 (SATA) Highlights

- Wide range of form factors and dimensions available, including type 2230, 2242, 2260, and 2280.
- iData Guard™, iPower Guard™ and iCell™ technology for data protection and integrity in case of abnormal power failure.
- Supports iSMART™ disk health monitoring.

Model Name	M.2 (S30) 3ME4	M.2 (S42) 3SE4
Key Features	1. Type 2230-D2-B-M 2. Exclusive L^3 architecture 3. Designed with LDPC ECC engine 4. Budget-friendly MLC-based solution	1. Type 2242-D2-B-M 2. High-quality SLC-based solution 3. DRAM-less, high-level data integrity 4. LDPC technology secures SSD reliability 5. Excellent data transfer speed
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	MLC	SLC
Capacity	8GB~128GB	8GB~64GB
Max. Channel	2	2
Sequential R/W (MB/sec, max.)	520/120	520/360
Max. Power Consumption	1.6W (3.3V x 505mA)	0.6W (3.3V x 185mA)
Thermal Sensor	Y	Y
External DRAM Buffer	N	N
iData Guard	Y	Y
iCell	N	N
TRIM	Y	Y
ATA Security	Y	Y
S.M.A.R.T	Y	Y
Dimension (WxLxH/mm)	22.0 x 42.0 x 3.2	22.0 x 42.0 x 3.5
Environment	Shock: 1500G@0.5ms/Storage Temperature: -55℃ ~ +95℃/ MTBF: >3 million hours	
Standard Temp. OP (0℃~+70℃)	DEM23-XXXM41BC***	DEM24-XXXM41SC***
Wide Temp. OP (-40℃~+85℃)	DEM23-XXXM41BW***	DEM24-XXXM41SW***
Note	XXX = density (02GB=02G, 04GB=04G, 08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G, 128GB=A28, 256GB=B56, 512GB=C12)***= flash configuration (internal control code) %=Flash Type	

Dimensions (mm)

Type 2230 Type 2242 Type 2260 Type2280

Model Name	M.2 (S42) 3IE4	M.2 (S42) 3ME4	M.2 (S42) 3MG2-P	M.2 (S42) 3TE7	M.2 (S42) 3TG6-P
Key Features	1. Type 2242-D2-B-M 2. Designed with LDPC ECC engine 3. Lifespan 7 times longer than MLC 4. Cost-effective industrial flash with iSLC	1. Type 2242-D2-B-M 2. Exclusive L³ architecture 3. Designed with LDPC ECC engine 4. Budget-friendly MLC-based solution	1. Type 2242-D2-B-M 2. High sequential/IOPS performance 3. Supports DEVSLP 4. iData Guard data protection	1. Type=2242-D2-B-M 2. Industrial-grade firmware with 3D NAND 3. Advanced LDPC ECC engine 4. Internal RAID Technology 5. DRAM-less, high-level data integrity 6. Excellent data transfer speed	1. Type=2242-D2-B-M 2. Extreme seq. and random performance with 3D NAND solution 3. Advanced LDPC ECC engine 4. RAID engine offers an additional level of data protection
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	iSLC	MLC	MLC	3D TLC	3D TLC
Capacity	8GB~128GB	8GB~256GB	32GB~256GB	32GB~512GB	128GB~512GB
Max. Channel	2	2	4	4	4
Sequential R/W (MB/sec, max.)	530/380	530/210	560/360	560/330	560/510
Max. Power Consumption	1.5W (3.3V x 460mA)	1.4W (3.3V x 422mA)	1.09 W (3.3V x330mA)	1.6W (3.3V x 475mA)	2.4W (3.3V x 739mA)
Thermal Sensor	Y	Y	Y	Y	Y
External DRAM Buffer	N	N	Y	N	Y
iData Guard	Y	Y	Y	Y	Y
iCell	N	N	N	N	N
TRIM	Y	Y	Y	Y	Y
ATA Security	Y	Y	Y	Y	Y
S.M.A.R.T	Y	Y	Y	Y	Y
Dimension (WxLxH/mm)	22.0 x 42.0 x 3.2	22.0 x 42.0 x 3.2	22.0 x 42.0 x 3.5	22.0 x 42.0 x 3.5	22.0 x 42.0 x 3.5
Environment	Shock: 1500G@0.5ms/Storage Temperature: -55℃ ~ +95℃/MTBF: >3 million hours				
Standard Temp. OP (0℃~+70℃)	DHM24-XXXM41BC***	DEM24-XXXM41BC***	DGM24-XXX-D81%C***	DEM24-XXXDK1EC***	DGM24-XXXM71EC***
Wide Temp. OP (-40℃~+85℃)	DHM24-XXXM41BW***	DEM24-XXXM41BW***	DGM24-XXX-D81%W***	DEM24-XXXDK1EW***	DGM24-XXXM71EW***
Note	XXX = density (02GB=02G, 04GB=04G, 08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G, 128GB=A28, 256GB=B56, 512GB=C12) ***= flash configuration (internal control code) %=Flash Type				

Model Name	M.2 (S60) 3ME3	M.2 (S80) 3SE4	M.2 (S80) 3IE4	M.2 (S80) 3ME4
Key Features	1. Type 2260-D2-B-M 2. High IOPS 3. iData Guard data protection	1. Type 2280-S2-B-M (single side) 2. High-quality SLC-based solution 3. DRAM-less, high-level data integrity 4. LDPC technology secures SSD reliability 5. Excellent data transfer speed	1. Type 2280-D2-B-M 2. Designed with LDPC ECC engine 3. Lifespan 7 times longer than MLC 4. Cost-effective industrial flash with iSLC	1. Type 2280-D2-B-M 2. Exclusive L³ architecture 3. Designed with LDPC ECC engine 4. Budget-friendly MLC-based solution
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	MLC	SLC	iSLC	MLC
Capacity	32GB~512GB	8GB~64GB	8GB~128GB	8GB~256GB
Max. Channel	4	2	2	2
Sequential R/W (MB/sec, max.)	380/200	520/360	530/360	530/210
Max. Power Consumption	1.3W (3.3V x 370mA)	1.6W (3.3V x 500 mA)	0.9 W (3.3V x 270mA)	0.9 W (3.3V x 270mA)
Thermal Sensor	STD: N, W/T: Y	Y	Y	Y
External DRAM Buffer	N	N	N	N
iData Guard	Y	Y	Y	Y
iCell	N	N	N	N
TRIM	Y	Y	Y	Y
ATA Security	Y	Y	Y	Y
S.M.A.R.T	Y	Y	Y	Y
Dimension (WxLxH/mm)	22.0 x 60.0 x 3.5	22.0 x 80.0 x 3.2	22.0 x 80.0 x 3.2	22.0 x 80.0 x 3.2
Environment	Shock: 1500G@0.5ms/Storage Temperature: -55℃ ~ +95℃/MTBF: >3 million hours			
Standard Temp. OP (0℃~+70℃)	DEM26-XXXD08%C***	DEM28-XXXM41SC***	DHM28-XXXM41BC***	DEM28-XXXM41BC***
Wide Temp. OP (-40℃~+85℃)	DEM26-XXXD08%W***	DEM28-XXXM41SW***	DHM28-XXXM41BW***	DEM28-XXXM41BW***
Note	XXX = density (02GB=02G, 04GB=04G, 08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G, 128GB=A28, 256GB=B56, 512GB=C12) ***= flash configuration (internal control code) %=Flash Type			

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Model Name	M.2 (S80) 3MG2-P	M.2 (S80) 3TE7	M.2 (S80) 3TG6-P
Key Features	1. Type 2280-D2-B-M 2. High sequential/IOPS performance 3. Supports DEVSLP 4. iData Guard data protection	1. Industrial-grade firmware with 3D NAND 2. Advanced LDPC ECC engine 3. Internal RAID technology 4. DRAM-less, high-level data integrity 5. Excellent data transfer speed 6. Type-2280-D2-B-M	1. Extreme seq. and random performance with 3D NAND solution 2. Advanced LDPC ECC engine 3. RAID engine offers an additional level of data protection 4. AES 256-key end-to-end data path protection 5. Type-2280-D2-B-M
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	MLC	3D TLC	3D TLC
Capacity	16GB~1TB	32GB~1TB	128GB~1TB
Max. Channel	4	4	4
Sequential R/W (MB/sec, max.)	530/450	550/370	560/510
Max. Power Consumption	3.63W (3.3V x 1.1A)	2.0W (3.3V x 614mA)	2.6W (3.3V x 799mA)
Thermal Sensor	Y	Y	Y
External DRAM Buffer	Y	N	Y
iData Guard	Y	Y	Y
iCell	Optional	N	N
TRIM	Y	Y	Y
ATA Security	Y	Y	Y
S.M.A.R.T	Y	Y	Y
Dimension (WxLxH/mm)	22.0 x 80.0 x 3.5	22.0 x 80.0 x 3.5	22.0 x 80.0 x 3.5
Environment	Shock: 1500G@0.5ms/Storage Temperature: -55°C ~ +95°C/MTBF: >3 million hours		
Standard Temp. OP (0°C~+70°C)	DGM28-XXXD81%C***	DEM28-XXXDK1EC***	DGM28-XXXM71EC***
Wide Temp. OP (-40°C~+85°C)	DGM28-XXXD81%W***	DEM28-XXXDK1EW***	DGM28-XXXM71EW***
Note	XX = density (02GB=02G, 04GB=04G, 08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G, 128GB=A28, 256GB=B56, 512GB=C12) ***= flash configuration (internal control code) %=Flash Type		

SSD

Innodisk's SSDs bring a whole new level of performance to memory storage. Our wide selection of SSDs is designed for different applications, including industrial/embedded, enterprise server, aviation, defense, as well as other semi-industrial applications, such as thin clients, POS systems, and kiosks. Our SSDs come in 3D TLC, iSLC, SLC, and MLC types, and support PATA/IDE 44-pin, SATA II (3.0Gb/s), and SATA III (6.0Gb/s).

Model Name	2.5" SATA SSD 3TE7	2.5" SATA SSD 3TG6-P	2.5" SATA SSD 3SE4
Key Features	1. Industrial-grade firmware with 3D NAND 2. Advanced LDPC ECC engine 3. Internal RAID technology 4. DRAM-less, high-level data integrity 5. Excellent data transfer speed	1. Extreme seq. and random performance with 3D NAND solution 2. Advanced LDPC ECC engine 3. RAID engine offers an additional level of data protection	1. High-quality SLC-based solution 2. DRAM-less, high-level data integrity 3. LDPC technology secures SSD reliability 4. Excellent data transfer speed
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	3D TLC	3D TLC	SLC
Capacity	32GB~1TB	128GB~4TB	8GB~64GB *For128GB, please check 2.5"SATA SSD 3SE3
Max. Channel	4	4	2
Sequential R/W (MB/sec, max.)	560/340	540 /470	520/360
Max. Power Consumption	3.6W (5V x 722mA)	128GB~1TB 3.1W (5V x 620mA) 2TB~4TB 6W (5V x 1.2A)	1.1W (5V x 220 mA)
Thermal Sensor	Y		
External DRAM Buffer	N	Y	N
iData Guard	Y	Y	Y
iCell	N	Optional	N
TRIM	Optional	Y	Y
ATA Security	Y	Y	Y
S.M.A.R.T	Y	Y	Y
Dimension (WxLxH/mm)	69.85 x 100.1 x 6.9	69.8 x 100.1 x 6.9	69.85 x 100.1 x 6.9
Environment	Vibration: 20G@7~2000Hz/Shock: 1500G@0.5ms/Storage Temperature: -55°C ~ +95°C/MTBF: >3 million hours		
Standard Temp. OP (0°C~+70°C)	DES25-XXXDK1EC***	DGS25-XXXM71EC***	DES25-XXXM41SC***
Wide Temp. OP (-40°C~+85°C)	DES25-XXXDK1EW***	DGS25-XXXM71EW***	DES25-XXXM41SW***
Notes	XXX = density (02GB=02G, 04GB=04G, 08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G, 128GB=A28, 256GB=B56, 512GB=C12, 1TB=01T, 2TB=02T) ***= flash configuration (internal control code) %=Flash		

| Model Name	2.5" SATA SSD 3SE2-P	2.5" SATA SSD 3SR3-P	2.5" SATA SSD 3IE4
Key Features	1. High IOPS performance with DRAM solution 2. High-quality SLC-based solution 3. Supports AES function	1. Compliant with MIL-STD-810G 2. H/W & S/W Data Security (Quick Erase/ Destroy/Security Erase/ Write Protect) 3. iCell supported, 100% data protection	1. Exclusive L^3 architecture 2. Designed with LDPC ECC engine 3. Cost-effective industrial flash with iSLC 4. Lifespan 7 times longer than MLC
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	SLC	SLC	iSLC
Capacity	8GB~512GB	8GB~256GB	8GB~128GB *For 256GB, please check 2.5"SATA S SD 3IE3
Max. Channel	4	4	2
Sequential R/W (MB/sec, max.)	520/420	490/240	530/380
Max. Power Consumption	2.15W (5V x 430mA)	2.65W (5V x 530mA)	0.8W (5V x 160mA)
Thermal Sensor		Y	
External DRAM Buffer	Y	Y	N
iData Guard	Y	Y	Y
iCell	Optional	Y	N
TRIM	Y	Y	Y
ATA Security	Y	Y	Y
S.M.A.R.T	Y	Y	Y
Dimension (WxLxH/mm)	69.8 x 99.8 x 9.2	69.8 x 99.8 x 9.2	69.8 x 100.1 x 6.9
Environment	Vibration: 20G@7~2000Hz/Shock: 1500G@0.5ms/Storage Temperature: -55°C ~ +95°C/MTBF: >3 million hours		
Standard Temp. OP (0°C~+70°C)	DES25-XXXD82SC***	DRS25-XXXD70SC***	DHS25-XXXM41%C***
Wide Temp. OP (-40°C~+85°C)	DES25-XXXD82SW***	DRS25-XXXD70SW***	DHS25-XXXM41%W***
Notes	XXX = density (02GB=02G, 04GB=04G, 08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G, 128GB=A28, 256GB=B56, 512GB=C12, 1TB=01T, 2TB=02T) ***= flash configuration (internal control code) %=Flash		

| Model Name	2.5" SATA SSD 3ME4	2.5" SATA SSD 3MG2-P	2,5" SATA SSD 3MR2-P
Key Features	1. Exclusive L^3 architecture 2. Designed with LDPC ECC engine 3. Excellent IOPS performance	1. EverGreen L^2 architecture 2. High Sequential/IOPS performance 3. Support DEVSLP 4. iData Guard data protection	1. Compliant with MIL-STD-810G 2. H/W & S/W Data Security (Quick Erase/ Destroy/Security Erase/Write Protect) 3. High random performance 4. iCell supported, 100% data protection
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	MLC	MLC	MLC
Capacity	8GB~256GB	8GB~2TB	8GB~2TB
Max. Channel	2	4	4
Sequential R/W (MB/sec, max.)	530/210	520/480	520/450
Max. Power Consumption	0.8W (5V x 160mA)	6W (5V x 1.2A)	6W (5V x 1.2mA)
Thermal Sensor		Y	Y
External DRAM Buffer	N	Y	Y
iData Guard	Y	Y	Y
iCell	N	Optional	Y
TRIM	Y	Y	Y
ATA Security	Y	Y	Y
S.M.A.R.T	Y	Y	Y
Dimension (WxLxH/mm)	69.8 x 100.10 x 6.9	69.8 x 100.1 x 6.9 69.8 x 100.0 x 9.5 (2TB)	69.8 x 99.8 x 9.2
Environment	Vibration: 20G@7~2000Hz/Shock: 1500G@0.5ms/Storage Temperature: -55°C ~ +95°C/MTBF: >3 million hours		
Standard Temp. OP (0°C~+70°C)	DES25-XXXM41%C***	DGS25-XXXD81%C***(P)	DRS25-XXXD82%C***P
Wide Temp. OP (-40°C~+85°C)	DES25-XXXM41%W***	DRS25-XXXD81%W***P	DRS25-XXXD82%W***
Notes	XXX = density (02GB=02G, 04GB=04G, 08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G, 128GB=A28, 256GB=B56, 512GB=C12, 1TB=01T, 2TB=02T) ***= flash configuration (internal control code) %=Flash		

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| Model Name	1.8 " SATA SSD 3TG6-P	1.8" SATA SSD 3MG2-P	Slim SSD 3ME4	PATA 1MG3-P
Key Features	1. Extreme seq. and random performance with 3D NAND solution 2. Advanced LDPC ECC engine 3. RAID engine offers an additional level of data protection 4. AES 256-key end-to-end data path protection	1. Built-in DRAM buffer 2. Intelligent error recovery system 3. Excellent data transfer speed and high IOPS performance 4. iData Guard for abnormal power failure	1. 1.8" housing, 50% space saving 2. Exclusive L^3 architecture 3. Designed with LDPC ECC engine	1. Built-in DRAM buffer 2. Intelligent error recovery system 3. Excellent data transfer speed 4. iData Guard data protection
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	PIO Mode 0~4 Ultra DMA 0~5
Flash Type	3D TLC	MLC	MLC	MLC
Capacity	32GB~1TB	32GB~1TB	8GB~256GB	8GB~512GB
Max. Channel	4	4	2	4
Sequential R/W (MB/sec, max.)	540 /470	520/450	530/210	90/90
Max. Power Consumption	0.8W (5V x 160mA)	6W (5V x 1.2A)	0.8W (5V x 160mA)	2W (5V x 400mA)
Thermal Sensor	Y	Y	Y	STD : N , W/T : Y
External DRAM Buffer	Y	Y	Y	Y
iData Guard	Y	Y	Y	Y
iCell	Optional	N	N	N
TRIM	Y	Y	Y	Y
ATA Security	Y	Y	Y	Y
S.M.A.R.T	Y	Y	Y	Y
Dimension (WxLxH/mm)	54.0 x 78.5 x 5.0	54.0 x 78.5 x 5.0	69.85 x 50.0 x 9.0	69.85 x 99.85 x 9.2
Environment	Vibration: 20G@7~2000Hz/Shock: 1500G@0.5ms/Storage Temperature: -55°C ~ +95°C/MTBF: >3 million hours			
Standard Temp. OP (0°C~+70°C)	DGS18-XXXM71EC***	DGS18-XXXD81SC***	DEMLM-XXXM41%C***	DGP25-XXXD70%C***
Wide Temp. OP (-40°C~+85°C)	DGS18-XXXM71EW***	DGS18-XXXD82%W***	DEMLM-XXXM41%W***	N/A
Notes	XXX = density (02GB=02G, 04GB=04G, 08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G, 128GB=A28, 256GB=B56, 512GB=C12, 1TB=01T, 2TB=02T) ***= flash configuration (internal control code) %=Flash			

What is iCell?
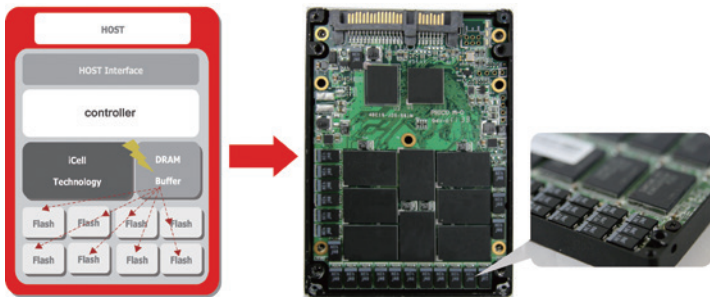
iCell technology gives the SSD a power boost in the event of an abnormal power failure and ensures reliable and accurate data transfer from DRAM cache to NAND flash.
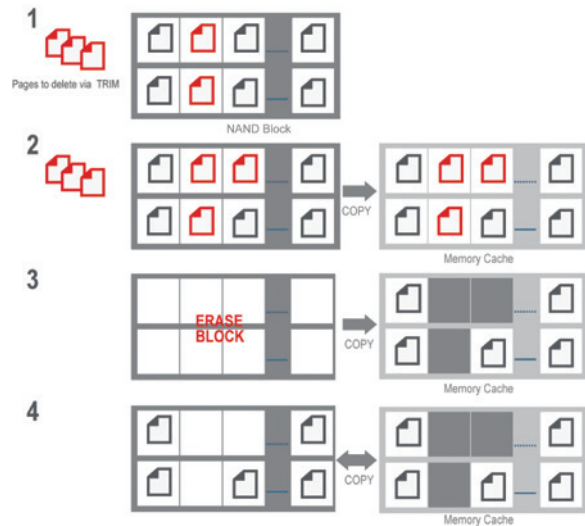
What is iSecurity?
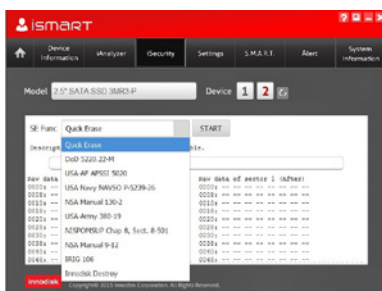
The iSecurity function under iSMART allows the user to easily operate the data erase command. The user may select the data erase function, monitor the erase progress and also compare data before and after the erasure.

What is TRIM?

SSDs are made up of millions of NAND flash cells. They can be written into groups called pages (generally 4KB in size) but can only be erased in larger groups called blocks (generally 128 pages or 512KB). The addresses of the deleted files are sent along with the TRIM command to the SSD's controller so the drive can function optimally. The TRIM commands allow the SSD to delete data more expediently, thus increasing overall performance. The TRIM command is generally sent from the OS when the system is idle. This cleans up invalid data from the blocks so the drive can continue performing like new.

SATADOM®

Innodisk's Serial ATA Disk on Module (SATADOM®) is the world's smallest form factor with exclusive built-in Pin 7 and Pin 8 VCC, which simplifies motherboard design. Since it has no external cables, it is more robust and enhances the disk functions of various industrial and enterprise applications. Innodisk's SATADOM® also supports the SATA II and SATA III interfaces with faster data transfer rates and is available in capacities ranging from 512MB up to 256GB.

SATADOM-SL 3ME4

Innodisk's SATADOM-SL 3ME4 features our patented Pin 7 and Pin 8 cable-less SATA power combined with our exclusive L^3 architecture. Thanks to these innovative features, the SATADOM-SL 3ME4 offers exceptional performance and reliability with a prolonged lifespan—making it the industry's best storage design for industrial computers and server boot drives. In 2017, the Innodisk SATADOM-SL 3ME4 won the Taiwan Excellence Award in the highly competitive category of "Computer Hardware and Peripheral Equipment," further highlighting the strength of its groundbreaking industrial design.

3ME4 series
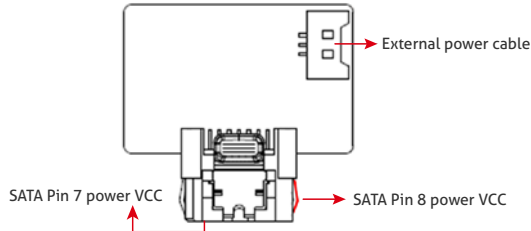- High performance
- LDPC
- Low WAI
- Supports S.M.A.R.T.

SATADOM-SL
- Tiny size
- Cable-less (Pin 8/ Pin 7 supported)
- OS boot drive
- Durable

Flexible power supply design

- External power cable
- SATA Pin 8 VCC
- SATA Pin 7 VCC

External power cable

SATA Pin 7 power VCC

SATA Pin 8 power VCC

Form Factor	SATADOM-SV/SH			
Model Name	**SATADOM 3TE7**	**SATADOM 3SE4**	**SATADOM 3IE4**	**SATADOM 3ME4**
Key Features	1. Industrial-grade firmware with 3D NAND 2. Advanced LDPC ECC engine 3. Internal RAID technology 4. DRAM-less, high-level data integrity 5. Excellent data transfer speed	1. High-quality SLC-based solution 2. DRAM-less, high-level data integrity 3. LDPC technology secures SSD reliability 4. Excellent data transfer speed	1. Cost-effective industrial flash with iSLC 2. Exclusive L^3 architecture 3. Latest LDPC ECC engine 4. Pin 8/Pin 7 supported	1. Vertical and low-profile horizontal design 2. Exclusive L^3 architecture 3. Latest LDPC ECC engine 4. High IOPS 5. Pin 8/Pin 7 supported
Interface	SATA III 6Gb/s	SATA III 6Gb/s	SATA III 6Gb/s	SATA III 6Gb/s
Flash Type	3D TLC	SLC	iSLC	MLC
Capacity	32GB~256GB	8GB~32GB	8GB~64GB	8GB~128GB
Max. Channel	2	2	2	2
Sequential R/W (MB/sec, max.)	510/300	520/260	530/350	530/120
Max. Power Consumption	1.55W (5V x 309mA)	1.58W (5V x 315mA)	0.95W (5V x 189mA)	1.27W (5V x 254mA)
Thermal Sensor	Y	Y	Y	Y
External DRAM Buffer	N	N	N	N
iData Guard	Y	Y	Y	Y
iCell	N	N	N	N
TRIM	Y	Y	Y	Y
ATA Security	Y	Y	Y	Y
S.M.A.R.T	Y	Y	Y	Y
Dimension (WxLxH/mm)	SV: 40.4 x 21.03 x 10.4 SH: 32.7 x 18 x 14.15	SV: 40.4 x 21.03 x 10.4 SH: 32.7 x 18 x 14.15	SV:40.4 x 21.03 x 10.4	SV: 40.4 x 21.03 x 10.4 SH: 32.7 x 18 x 15.15
Environment	Vibration: 20G@7~2000Hz Shock: 1500G@0.5ms Storage Temperature: -55°C ~ +95°C MTBF: >3 million hours			
Standard Temp. OP (0°C~+70°C)	SV: DESSV-XXXDK1EC***# SH: DESSH-XXXDK1EC***#	SV: DESSV-XXXM41SC***# SH: DESSH-XXXM41SC***#	SV: DHSSV-XXXM41BC***#	SV: DESSV-XXXM41BC***# SH: DESSH-XXXM41BC***#
Wide Temp. OP (-40°C~+85°C)	SV: DESSV-XXXDK1EW***# SH: DESSH-XXXDK1EW***#	SV: DESSV-XXXM41SW***# SH: DESSH-XXXM41SW***#	SV: DHSSV-XXXM41BW***#	SV: DESSV-XXXM41BW***# SH: DESSH-XXXM41BW***#
Notes	xxx = density (08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G, 128GB=A28, 256GB=B56, 512GB=C12) ***= flash configuration (internal control code) #=power supply method(A=pin 8+ external power cable / B=Pin 7+ Pin 8) *For SLC 01GB~4GB, please check FF 3SE or 3SE3			

Form Factor	SATADOM-SL/SH Type D			
Model Name	**SATADOM 3TE7**	**SATADOM 3SE4**	**SATADOM 3IE4**	**SATADOM 3ME4**
Key Features	1. Industrial-grade firmware with 3D NAND 2. Advanced LDPC ECC engine 3. Internal RAID technology 4. DRAM-less, high-level data integrity 5. Excellent data transfer speed	1. High-quality SLC-based solution 2. DRAM-less, high-level data integrity 3. LDPC technology secures SSD reliability 4. Excellent data transfer speed	1. The best boot solution under 1U 2. Cost-effective industrial flash with iSLC 3. Exclusive L^3 architecture 4. Latest LDPC ECC engine 5. Pin 8/Pin 7 supported	1. The best boot solution under 1U 2. Exclusive L^3 architecture 3. Latest LDPC ECC engine 4. High IOPS 5. Pin 8/Pin 7 supported
Interface	SATA III 6Gb/s	SATA III 6Gb/s	SATA III 6Gb/s	SATA III 6Gb/s
Flash Type	3D TLC	SLC	iSLC	MLC
Capacity	32GB~256GB	8GB~32GB	8GB~64GB	8GB~128GB
Max. Channel	2	2	2	2
Sequential R/W (MB/sec, max.)	510/300	520/260	530/350	530/120
Max. Power Consumption	1.5W (5V x 300mA)	0.95W (5V x 186mA)	1.02W (5V x 204mA)	1.02W (5V x 204mA)
Thermal Sensor	Y	Y	Y	Y
External DRAM Buffer	N	N	N	N
iData Guard	Y	Y	Y	Y
iCell	N	N	N	N
TRIM	Y	Y	Y	Y
ATA Security	Y	Y	Y	Y
S.M.A.R.T	Y	Y	Y	Y
Dimension (WxLxH/mm)	SL: 29.6 x 33.06 x 10.5 SH(D):30 x 20.79 x 15.20	SL: 29.6 x 33.06 x 10.5 SH(D):30 x 20.79 x 15.15	SL: 29.6 x 33.06 x 10.5	SL: 29.6 x 33.06 x 10.5 SH(D): 30 x 20.79 x 15.15
Environment	Vibration: 20G@7~2000Hz Shock: 1500G@0.5ms Storage Temperature: -55°C ~ +95°C MTBF: >3 million hours			
Standard Temp. OP (0°C~+70°C)	SL: DESSL-XXXDK1EC***# SH(D): DESSF-XXXDK1EC***#	SL: DESSL-XXXM41SC***# SH(D): DESSF-XXXM41SC***#	SL: DHSSL-XXXM41BC***#	SL: DESSL-XXXM41BC***# SH(D): DESSF-XXXM41BC***#
Wide Temp. OP (-40°C~+85°C)	SL: DESSL-XXXDK1EW***# SH(D): DESSF-XXXDK1EW***#	SL: DESSL-XXXM41SW***# SH(D): DESSF-XXXM41SW***#	SL: DHSSL-XXXM41BW***#	SL: DESSL-XXXM41BW***# SH(D): DESSF-XXXM41BW***#
Notes	xxx = density (08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G, 128GB=A28, 256GB=B56, 512GB=C12) ***= flash configuration (internal control code) #=power supply method(A=pin 8+ external power cable / B=Pin 7+ Pin 8) *For SLC 01GB~4GB, please check FF 3SE or 3SE3			

Form Factor	SATADOM-ML/MH				
Model Name	**SATADOM 3SE4**	**SATADOM 3IE4**	**SATADOM 3ME4**	**SATADOM 3TG6-P**	**SATADOM 3MG2-P**
Key Features	1. High-quality SLC-based solution 2. DRAM-less, high-level data integrity 3. LDPC technology secures SSD reliability 4. Excellent data transferspeed	1. Supports hardware write protection 2. Cost-effective industrial flash with iSLC 3. Exclusive L^3 architecture 4. Latest LDPC ECC engine 5. High IOPS 6. Pin 8/Pin 7 supported	1. Supports hardware write protection 2. Exclusive L^3 architecture 3. Latest LDPC ECC engine 4. High IOPS 5. Pin 8/Pin 7 supported	1. Extreme seq. and random performance with 3D NAND solution 2. Advanced LDPC ECC engine 3. RAID engine offers an additional level of data protection 4. AES 256-key end-to-end data path protection	1. Supports hardware write protection 2. High IOPS 3. High performance SATADOM
Interface	SATA III 6.0Gb/s	SATA III 6Gb/s	SATA III 6Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	SLC	iSLC	MLC	3D TLC	MLC
Capacity	8GB~64GB	16GB~128GB	32GB~256GB	128GB~256GB	32GB-256GB
Max. Channel	2	2	2	4	4
Sequential R/W (MB/sec, max.)	520/360	530/360	530/210	560/290	560/180
Max. Power Consumption	1.58W(5V x 315mA)	0.815W(5V x 163mA)	0.815W(5V x 163mA)	2.14W(5V x 428mA)	2.68W(5V x 535mA)
Thermal Sensor	Y	Y	Y	Y	Y
External DRAM Buffer	N	N	N	Y	Y
iData Guard	Y	Y	Y	Y	Y
iCell	N	N	N	N	N
TRIM	Y	Y	Y	Y	Y
ATA Security	Y	Y	Y	Y	Y
S.M.A.R.T	Y	Y	Y	Y	Y
Dimension (WxLxH/mm)	ML: 36.7 x 31.2 x 10.7	ML: 31.2 x 36.7 x 10.7 MH: 23.5 x 33.6 x 14.8	ML: 31.2 x 36.7 x 10.7 MH: 23.5 x 33.6 x 14.8	ML: 37.17 x 31.5 x 12.6	ML: 37.17 x 31.5 x 12.6
Environment	Vibration: 20G@7~2000Hz Shock: 1500G@0.5ms Storage Temperature: -55°C ~ +95°C MTBF: >3 million hours				
Standard Temp. OP (0°C~+70°C)	ML: DESML-XXXM41SC***# MH: DESMH-XXXM-41SC***#	ML: DHSML-XXX-M41BC***# MH: DHSMH-XXX-M41BC***#	ML: DESML-XXX-M41BC***# MH: DESMH-XXX-M41BC***#"	ML: DGSML-XXXM71EC***#	ML: DGSML-XXXD81BC***#
Wide Temp. OP (-40°C~+85°C)	ML: DESML-XXXM-41SW***# MH: DESMH-XXXM-41SW***#	ML: DHSML-XXX-M41BW***# MH: DHSMH-XXX-M41BW***#	ML: DESML-XXX-M41BW***# MH: DESMH-XXX-M41BW***#	ML: DGSML-XXXM71EW***#	ML: DGSML-XXXD81BW***#
Notes	xxx = density (08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G, 128GB=A28, 256GB=B56, 512GB=C12) ***= flash configuration (internal control code) #=power supply method(A=pin 8+ external power cable / B=Pin 7+ Pin 8) *For SLC 01GB~4GB, please check FF 3SE or 3SE3				

Form Factor	SATADOM-SH type C		SATADOM-MV	
Model Name	**SATADOM 3SE4**	**SATADOM 3ME4**	**SATADOM 3IE4**	**SATADOM 3ME4**
Key Features	1. High-quality SLC-based solution 2. DRAM-less, high-level data integrity 3. LDPC technology secures SSD reliability 4. Excellent data transfer speed	1. Low-profile horizontal design. 2. Exclusive L³ architecture 3. Latest LDPC ECC engine 4. High IOPS 5. Pin 8/Pin 7 supported	1. Supports hardware write protection 2. Cost-effective industrial flash with iSLC 3. Exclusive L³ architecture 4. Latest LDPC ECC engine 5. High IOPS 6. Pin 8/Pin 7 supported	1. Supports hardware write protection 2. Exclusive L³ architecture 3. Latest LDPC ECC engine 4. High IOPS 5. Pin 8/Pin 7 supported
Interface	SATA III 6.0Gb/s	SATA III 6Gb/s	SATA III 6Gb/s	SATA III 6Gb/s
Flash Type	SLC	MLC	iSLC	MLC
Capacity	8GB~32GB	8GB~128GB	8GB~64GB	8GB~128GB
Max. Channel	2	2	2	2
Sequential R/W (MB/sec, max.)	520/260	530/120	530/340	530/120
Max. Power Consumption	1.49W(5V x 297mA)	1.02W(5V x 204mA)	1.72W(5V x 343mA)	1.08W(5V x 216mA)
Thermal Sensor	Y	Y	Y	Y
External DRAM Buffer	N	N	N	N
iData Guard	Y	Y	Y	Y
iCell	N	N	N	N
TRIM	Y	Y	Y	Y
ATA Security	Y	Y	Y	Y
S.M.A.R.T	Y	Y	Y	Y
Dimension (WxLxH/mm)	32.7 x 18 x 14.5 mm	32.7 x 18 x 14.5 mm	41.55 x 25.26 x 10.4 mm	41.55 x 25.26 x 10.4 mm
Environment	Vibration: 20G@7~2000Hz Shock: 1500G@0.5ms Storage Temperature: -55°C ~ +95°C MTBF: >3 million hours			
Standard Temp. OP (0°C~+70°C)	DESSC-XXXM41SC***#	DESSC-XXXM41BC***#	DHSMV-XXXM41BC***#	DESMV-XXXM41BC***#
Wide Temp. OP (-40°C~+85°C)	DESSC-XXXM41SW***#	DESSC-XXXM41BW***#	DHSMV-XXXM41BW***#	DESMV-XXXM41BW***#
Notes	xxx = density (08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G, 128GB=A28, 256GB=B56, 512GB=C12) ***= flash configuration (internal control code) #=power supply method(A=pin 8+ external power cable / B=Pin 7+ Pin 8) *For SLC 4GB, please check FF 3SE or 3SE3			

mSATA

mSATA, which is compliant with the JEDEC MO300/MO300B standard, was announced by the Serial ATA International Organization on September 21, 2009. Applications include netbooks, portable devices and other devices that require a smaller solid-state drive. The connector is similar in appearance to a PCI Express Mini Card interface and is electrically compatible; however, the data signals need a connection to the SATA host controller instead of the PCI-express host controller. Innodisk's mSATA supports high-performance data transfer rates of 1.5 Gb/s, 3.0 Gb/s, and 6.0 Gb/s.

Model Name	**mSATA 3TE7**	**mSATA 3TG6-P**
Key Features	1. Industrial-grade firmware with 3D NAND 2. Designed with LDPC ECC engine 3. Internal RAID technology 4. DRAM-less, high-level data integrity 5. Excellent data transfer speed	1. Extreme seq. and random performance with 3D NAND solution 2. Designed with LDPC ECC engine 3. RAID engine offers an additional level of data protection
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	3D TLC	3D TLC
Capacity	32GB~1TB	128GB~1TB
Max. Channel	4	4
Sequential R/W (MB/sec, max.)	560/340	560/510
Max. Power Consumption	2.2 W (3.3V x 674mA)	2.8 W (3.3V x 850mA)
Thermal Sensor	Y	Y
External DRAM Buffer	N	Y
iData Guard	Y	Y
iCell	Optional (64GB-512GB)	N
TRIM	Y	Y
ATA Security	Y	Y
S.M.A.R.T	Y	Y
Dimension (WxLxH/mm)	29.8 x 50.8 x 3.7	29.8 x 50.8 x 3.7
Environment	Vibration: 20G@7~2000Hz/Shock: 1500G@0.5ms/Storage Temperature: -55°C ~ +95°C/MTBF: >3 million hours***	
Standard Temp. OP (0°C~+70°C)	DEMSR-XXXDK1EC***	DGMSR-XXXM71EC***
Wide Temp. OP (-40°C~+85°C)	DEMSR-XXXDK1EW***	DGMSR-XXXM71EW***
Note	XXX = density (02GB=02G, 04GB=04G, 08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G) ***= flash configuration (internal control code)%=Flash Type	

Model Name	mSATA 3SE4	mSATA 3SE-P	mSATA 3IE4	mSATA 3MG2-P	mSATA 3ME4
Key Features	1. High-quality SLC-based solution 2. DRAM-less, high-level data integrity 3. LDPC technology secures SSD reliability 4. Excellent data transfer speed	1. Excellent data transfer speed and IOPS 2. Support TRIM command 3. Built-in DRAM buffer	1. Cost-effective industrial flash with iSLC 2. Lifespan 7 times longer than MLC 3. Performance and data quality congruent to SLC 4. Excellent data transfer speed 5. LDPC technology secures SSD reliability	1. High IOPS by on-board DRAM design 2. Featuring L² architecture, expanding the lifespan 3. DEVSLP supported	1. LDPC technology secures SSD reliability 2. DRAM-less, high-level data integrity
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	SLC	SLC	iSLC	MLC	MLC
Capacity	8GB~64GB *For 4GB/ 128GB, please check mSATA 3SE3	8GB~64GB	8GB~128GB	8GB~512GB	8GB~256GB *For 512 GB, please check mSATA 3ME3
Max. Channel	2	4	2	4	2
Sequential R/W (MB/sec, max.)	525/350	490/260	530/365	520/450	535/210
Max. Power Consumption	1.32W (3.3V x 400mA)	1.2 W (3.3V x 360mA)	0.6W (3.3V x 200mA)	2.2 W (3.3 V x 660mA)	0.6W (3.3V x 205mA)
Thermal Sensor	Y	STD : N, W/T : Y	Y	Y	Y
External DRAM Buffer	N	Y	N	Y	N
iData Guard	Y	Y	Y	Y	Y
iCell	N	N	N	N	N
TRIM	Y	Y	Y	Y	Y
ATA Security	Y	Y	Y	Y	Y
S.M.A.R.T	Y	Y	Y	Y	Y
Dimension (WxLxH/mm)	29.8 x 50.8 x 3.7	29.8 x 50.8 x 3.7	29.8 x 50.8 x 3.7	29.8 x 50.8 x 3.7	29.8 x 50.8 x 3.7
Environment	Vibration: 20G@7~2000Hz/Shock: 1500G@0.5ms/Storage Temperature: -55°C ~ +95°C/MTBF: >3 million hours***				
Standard Temp. OP (0°C~+70°C)	DEMSR-XXXM41SC***	DEMSR-XXXD67SC***	DHMSR-XXXM41BC***	DGMSR-XXXD81SC***	DEMSR-XXXM41BC***
Wide Temp. OP (-40°C~+85°C)	DEMSR-XXXM41SW***	DEMSR-XXXD67SW***	DHMSR-XXXM41BW***	DGMSR-XXXD81SW***	DEMSR-XXXM41BW***
Note	XXX = density (02GB=02G, 04GB=04G, 08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G) ***= flash configuration (internal control code)%=Flash Type				

Model Name	mSATA mini 3TE7	mSATA mini 3SE4	mSATA mini 3IE4	mSATA mini 3ME4
Key Features	1. Truly industrial designed firmware with 3D NAND 2. Designed with LDPC ECC engine 3. Internal RAID technology 4. DRAM-less, high-level data integrity 5. Excellent data transfer speed	1. High-quality SLC-based solution 2. DRAM-less, high-level data integrity 3. LDPC technology secures SSD reliability 4. Excellent data transfer speed	1. Cost-effective industrial flash with iSLC 2. Lifespan 7 times longer than MLC 3. Performance and data quality congruent to SLC 4. Excellent data transfer speed 5. LDPC technology secures SSD reliability	1. LDPC technology secures SSD reliability 2. DRAM-less, high-level data integrity
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	3D TLC	SLC	iSLC	MLC
Capacity	32GB~512GB	8GB~64GB *For 4GB, please check mSATA mini 3SE3	8GB~64GB	8GB~128GB
Max. Channel	4	2	2	2
Sequential R/W (MB/sec, max.)	560/330	525/360	530/340	430/125
Max. Power Consumption	0.6W (3.3V x 190mA)	1.3W (3.3 V x 400mA)	0.6W (3.3V x 200mA)	0.6W (3.3V x 190mA)
Thermal Sensor	Y	Y	Y	Y
External DRAM Buffer	N	N	N	N
iData Guard	Y	Y	Y	Y
iCell	N	N	N	N
TRIM	Y	Y	Y	Y
ATA Security	Y	Y	Y	Y
S.M.A.R.T	Y	Y	Y	Y
Dimension (WxLxH/mm)	30 x 26.8 x 3.6	30 x 26.8 x 3.4	30 x 26.8 x 3.4	30 x 26.8 x 3.4
Environment	Vibration: 20G@7~2000Hz/Shock: 1500G@0.5ms/Storage Temperature: -55°C ~ +95°C/MTBF: >3 million hours***			
Standard Temp. OP (0°C~+70°C)	DEMSM-XXXDK1EC***	DEMSM-XXXM41SC***	DHMSM-XXXM41BC***	DEMSM-XXXM41BC***
Wide Temp. OP (-40°C~+85°C)	DEMSM-XXXDK1EW***	DEMSM-XXXM41SW***	DHMSM-XXXM41BW**	DEMSM-XXXM41BW***
Note	XXX = density (02GB=02G, 04GB=04G, 08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G) ***= flash configuration (internal control code)%=Flash Type			

SATA Slim

The Innodisk SATA Slim is compliant with the JEDEC SFF-8156 standard form factor and ATA protocol. It does not require drivers, and can be configured as a boot device or a data storage device. It is also suitable for portable/hand-held devices, thin clients, and industrial applications that require the effective reduction of operation system boot time and power consumption. With a 7 + 15-pin SATA interface, the Innodisk SATA Slim supports most platforms with a standard SATA port.

Model Name	SATA Slim 3TE7	SATA Slim 3TG6-P	SATA Slim 3SE4
Key Features	1. Industrial-grade firmware with 3D NAND 2. Designed with LDPC ECC engine 3. Internal RAID technology 4. DRAM-less, high-level data integrity 5. Excellent data transfer speed	1. Extreme seq. and random performance with 3D NAND solution 2. Designed with LDPC ECC engine 3. RAID engine offers additional level of data protection	1. High-quality SLC-based solution 2. DRAM-less, high-level data integrity 3. LDPC technology secures SSD reliability 4. Excellent data transfer speed
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	3D TLC	3D TLC	SLC
Capacity	32GB~1TB	128GB~1TB	8GB~64GB *For128GB, please check SATA Slim 3SE3
Max. Channel	4	4	2
Sequential R/W (MB/sec, max.)	560/340	540/470	530/360
Max. Power Consumption	0.8W (5V x 160mA)	3.1W (5V x 620mA)	1.1 W (5V x 220mA)
Thermal Sensor	Y	Y	Y
External DRAM Buffer	N	Y	N
iData Guard	Y	Y	Y
iCell	N	N	N
TRIM	Y	Y	Y
ATA Security	Y	Y	Y
S.M.A.R.T	Y	Y	Y
Dimension (WxLxH/mm)	54.0 x 39.0 x 4.0	54.0 x 39.0 x 4.0	54.0 x 39.0 x 4.0
Environment	Vibration: 20G@7~2000Hz/Shock: 1500G@0.5ms/Storage Temperature: -55°C ~ +95°C/MTBF: >3 million		
Standard Temp. OP (0°C~+70°C)	DESLM-XXXDK1EC***	DGSLM-XXXM71EC***	DESLM-XXXM41SC***
Wide Temp. OP (-40°C~+85°C)	DESLM-XXXDK1EW***	DGSLM-XXXM71EW***	DESLM-XXXM41SW***
Notes	XXX = density (02GB=02G, 04GB=04G, 08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G, 128GB=A28, 256GB=B56, 512GB=C12) ***= flash configuration (internal control code) %=Flash Type		

Model Name	SATA Slim 3IE4	SATA Slim 3ME4	SATA Slim 3MG2-P
Key Features	1. Exclusive L^3 architecture 2. Designed with LDPC ECC engine 3. Cost-effective industrial flash with iSLC	1. Exclusive L^3 architecture 2. Designed with LDPC ECC engine 3. Compatible with JEDEC MO-297	1. EverGreen L^2 architecture 2. High Sequential/IOPS performance 3. Supports DEVSLP 4. iData Guard data protection
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Flash Type	iSLC	MLC	MLC
Capacity	8GB~128GB	8GB~128GB	8GB~256GB
Max. Channel	2	2	4
Sequential R/W (MB/sec, max.)	530/360	530/210	520/290
Max. Power Consumption	0.8W (5V x 160mA)	0.8W (5V x 160mA)	2.6W (5V x 520mA)
Thermal Sensor	Y	Y	STD : N, W/T : Y
External DRAM Buffer	N	N	Y
iData Guard	Y	Y	Y
iCell	N	N	N
TRIM	Y	Y	Y
ATA Security	Y	Y	Y
S.M.A.R.T	Y	Y	Y
Dimension (WxLxH/mm)	54.0 x 39.0 x 4.0	54.0 x 39.0 x 4.0	54.0 x 39.0 x 4.0
Environment	Vibration: 20G@7~2000Hz/Shock: 1500G@0.5ms/Storage Temperature: -55°C ~ +95°C/MTBF: >3 million		
Standard Temp. OP (0°C~+70°C)	DHSLM-XXXM41%C***	DESLM-XXXM41%C***	DGSLM-XXXD81%C***
Wide Temp. OP (-40°C~+85°C)	DHSLM-XXXM41%W***	DESLM-XXXM41%W***	DGSLM-XXXD81%W***
Notes	XXX = density (02GB=02G, 04GB=04G, 08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G, 128GB=A28, 256GB=B56, 512GB=C12) ***= flash configuration (internal control code) %=Flash Type		

innodisk

CFast

The Innodisk CFast is a small form factor card standard with high data storage capacity. It is particularly suitable for semi-industrial applications. Compliant with the CFast 2.0 standard, it is designed with a 7 + 17-pin connector and is SATA compatible. The Innodisk CFast offers data transfer rates of sequential read up to 560MB/sec and of sequential write up to 520MB/sec.

Model Name	CFast 3TE7	CFast 3SE4
Key Features	1. Industrial-grade firmware with 3D NAND 2. Designed with LDPC ECC engine 3. Internal RAID technology 4. DRAM-less, high-level data integrity 5. Excellent data transfer speed	1. High-quality SLC-based solution 2. DRAM-less, high-level data integrity 3. LDPC technology secures SSD reliability 4. Excellent data transfer speed
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Connector	7-pin + 17-pin	7-pin + 17-pin
Flash Type	3D TLC	SLC
Capacity	32GB~512GB	8GB~64GB
Max. Channel	4	2
Sequential R/W (MB/sec, max.)	560/330	530/360
Max. Power Consumption	1.81W (3.3V x 550mA)	1.59W (3.3V x 480mA)
Thermal Sensor	Y	Y
External DRAM Buffer	N	N
iData Guard	Y	Y
iCell	N	N
TRIM	Y	Y
ATA Security	Y	Y
S.M.A.R.T	Y	Y
Dimension (WxLxH/mm)	42.8 x 36.4 x 3.6	42.8 x 36.4 x 3.6
Environment	Vibration: 20G@7~2000Hz/Shock: 1500G@0.5ms/Storage Temperature: -55℃ ~ +95℃/MTBF: >3 million hours	
Standard Temp. OP (0℃~+70℃)	DECFA-XXXDK1EC***	DHCFA-XXXM41SC***
Wide Temp. OP (-40℃~+85℃)	DECFA-XXXDK1EW***	DECFA-XXXM41SW***
Note	xxx = density (08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G, 128GB=A28, 256GB=B56, 512GB=C12) ***= flash configuration (internal control code) %=Flash Type	

Model Name	CFast 3IE4	CFast 3ME4	CFast 3MG2-P
Key Features	1. Cost-effective industrial flash with iSLC 2. Lifespan 7 times longer than MLC 3. Excellent IOPS performance 4. Designed with LDPC ECC engine 5. Supports hardware write protection	1. Exclusive L^3 architecture 2. Designed with LDPC ECC engine 3. Excellent IOPS performance 4. Supports hardware write protection	1. Compliant with CFast 2.0 standard 2. EverGreen L^2 architecture 3. High sequential/IOPS performance 4. Supports DEVSLP 5. iData Guard data protection
Interface	SATA III 6.0Gb/s	SATA III 6.0Gb/s	SATA III 6.0Gb/s
Connector	7-pin + 17-pin	7-pin + 17-pin	7-pin + 17-pin
Flash Type	iSLC	MLC	MLC
Capacity	8GB~128GB	8GB~256GB	32GB~256GB
Max. Channel	2	2	4
Sequential R/W (MB/sec, max.)	530/360	530/210	560/350
Max. Power Consumption	0.76W (3.3V x 230mA)	0.86W (3.3V x 260mA)	2.51W (3.3V x 760mA)
Thermal Sensor	Y	Y	Y
External DRAM Buffer	N	N	Y
iData Guard	Y	Y	Y
iCell	N	N	N
TRIM	Y	Y	Y
ATA Security	Y	Y	Y
S.M.A.R.T	Y	Y	Y
Dimension (WxLxH/mm)	42.8 x 36.4 x 3.6	42.8 x 36.4 x 3.6	42.8 x 36.4 x 3.6
Environment	Vibration: 20G@7~2000Hz/Shock: 1500G@0.5ms/Storage Temperature: -55℃ ~ +95℃/MTBF: >3 million hours		
Standard Temp. OP (0℃~+70℃)	DHCFA-XXXM41BC***	DECFA-XXXM41BC***	DGCFA-XXXD81BC***
Wide Temp. OP (-40℃~+85℃)	DHCFA-XXXM41BW***	DECFA-XXXM41BW***	DGCFA-XXXD81BW***
Note	xxx = density (08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G, 128GB=A28, 256GB=B56) ***= flash configuration (internal control code) %=Flash Type		

CF Card

Innodisk's Industrial CompactFlash Memory Card (iCF) complies with the PCMCIA ATA standard. Designed to replace traditional rotating disk drives, Innodisk iCFs are embedded solid-state data storage systems that are designed for mobile computing and the industrial workplace.

Model Name	iCF 9000	iCF 1SE	iCF 1ME	iCF 1SE2
Key Features	1. High sustained data transfer speed 2. Enhanced power cycling management	High-quality SLC-based solution	1. Budget-friendly MLC-based solution 2. Enhanced power cycling management	1. High-quality SLC-based solution 2. Enhanced power cycling management
Interface	PATA	PATA	PATA	PATA
Connector	50-pin CF connector	50-pin CF connector	50-pin CF connector	50-pin CF connector
Flash Type	SLC	SLC	MLC	SLC
Capacity	1GB~64GB	512MB~8GB	8GB~256GB	1GB~64GB
Max. Channel	4	2	2	2
Sequential R/W (MB/sec, max.)	110/100	40/30	110/110	75/65
Max. Power Consumption	0.95W (5V x 190mA) 0.63W (3.3V x 190mA)	0.75W (5V x 150mA) 0.5W (3.3V x 150mA)	0.76W (5V x 155mA) 0.52W (3.3V x 155 mA)	TBD
Thermal Sensor	N	N	N	N
ATA Security	Y	Y	Y	Y
S.M.A.R.T	Y	Y	Y	Y
Dimension (WxLxH/mm)	42.8 x 36.4 x 3.3	42.8 x 36.4 x 3.3	42.8 x 36.4 x 3.3	42.8 x 36.4 x 3.3
Environment	Vibration: 20G@7~2000Hz/Shock: 1500G@0.5ms/Storage Temperature: -55℃ ~ +95℃/MTBF: >3 million hours			
Standard Temp. OP (0℃~+70℃)	DC1M-XXXD71AC***	DC1M-XXXD41AC***	DECFC-XXXD53BC***	DECFC-XXXD53AC***
Wide Temp. OP (-40℃~+85℃)	DC1M-XXXD71AW***	DC1M-XXXD41AW***	DECFC-XXXD53BW***	DECFC-XXXD53AW***
Note	PIO mode 0-6 UDMA mode 0-7	PIO mode 0-6 UDMA mode 0-4	PIO mode 0-6 UDMA mode 0-7	"PIO mode 0-6 UDMA mode 0-7"
Notes	XXX = density (512MB=512, 01GB=01G, 02GB=02G, 04GB=04G, 08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G, 128GB=A28, 256GB=B56)***= flash configuration (internal control code) % =Flash Type			

SD/microSD

Innodisk's SD and microSD cards are single-level flash devices built for rugged applications in the embedded field. As industrial-grade SD and microSD cards, these products deliver excellent endurance and reliability, especially compared to cards used in the mobile market. Innodisk SD and microSD cards are compatible with SD 2.0 /SD 3.0 standards and support SDHC Class 10 (UHS-I). They also feature S.M.A.R.T. technology, which monitors the reliability of these SD cards.

Model Name	microSD 3SE3	Industrial microSD Card	microSD 3ME2	microSD 3IE2	Industrial SD Card	Industrial SD Card 3ME3
Key Features	Enhanced power cycling management	Enhanced power cycling management	1. Supports Class 10 with UHS-I 2. High performance 3. SPI mode supported	1. Supports Class 10 with UHS-I 2. High performance 3. SPI mode supported	1. Designed for industrial applications 2. High reliability 3. Customizeable 4. Power failure management 5. AES (optional)	1. High performance 2. Power failure management 3. BCH ECC implementation
Interface	SD 3.0	SD 2.0	SD 3.0	SD 3.0	SD 3.0	SD 3.0
Flash Type	SLC	SLC	MLC	iSLC	SLC/iSLC/MLC	MLC
Capacity	4GB~8GB	1GB~4GB	8GB~64GB	4GB~32GB	SLC: 128MB~32GB iSLC: 8GB~64GB MLC: 8GB~128GB	8GB~128GB
Max. Channel	1	1	1	1	1	1
Sequential R/W (MB/sec, max.)	30/23	20/16	75/31	79/45	SLC: 23/21 iSLC: 61/36 MLC: 54/18	80/46
Max. Power Consumption	01.2W (3.3V x 387mA)	0.17W (3.3V x 50mA)	0.7W (3.3V x 219mA)	0.7W (3.3V x 219mA)	0.22W (3.3V x 69mA) (SLC) 0.34W (3.3V x 105mA) (MLC)	0.56W (3.6V x 158mA)
S.M.A.R.T	Y	Y	Y	Y	Y	Y
Dimension (WxLxH/mm)	11.0 x 15.0 x 1.0	11.0 x 15.0 x 1.0	11.0 x 15.0 x 1.0	11.0 x 15.0 x 1.0	24.0 x 32.0 x 2.1	24.0 x 32.0 x 2.1
Environment	Vibration: 20G@7~2000Hz/Shock: 1500G@0.5ms/Storage Temperature: -55℃ ~ +95℃/MTBF: >3 million hours					
Standard Temp. OP (-25℃~+85℃)	DESDM-XXXS02AC*** DESDM-XXXS02AE***	DS2M-XXXI81AC***	DESDM-XXXE21SEASK	DHSDM-XXXE21SEASK	DESDC-XXXY81%C*** DHSDC-XXXY81%C***(iSLC)	DESDC-XXXS02BC***
Wide emp. OP (-40℃~+85℃)	DESDM-XXXS02AW***	DS2M-XXXI81AW***	DESDM-XXXE21SWASK	NA	DESDC-XXXY81%W*** DHSDC-XXXY81%W***(iSLC)	DESDC-XXXS02BW***
Note	XXX = density (02GB=02G, 04GB=04G, 08GB=08G)*** = flash configuration (internal control code) %=Flash Type					

EDC

The Innodisk Embedded Disk Card (EDC) complies with PCMCIA ATA standards and fits into all platforms with an IDE connector. The Innodisk Embedded Disk Card comes in capacities ranging from 512MB to 256GB and is available in 40-pin and 44-pin connector packages.

Model Name	EDC 1SE Vertical Type	EDC 1SE Horizontal Type	EDC 1ME Vertical Type	EDC 1ME Horizontal Type
Key Features	1. Dust prevention 2. High-quality SLC-based solution	1. High-quality SLC-based solution 2. Supported mounting hole	1. Budget-friendly MLC-based solution 2. High-performance PATA solution	1. Budget-friendly MLC-based solution 2. High-performance PATA solution
Connector	40/44-pin	40/44-pin	44-pin	44-pin
Interface	PATA	PATA	PATA	PATA
Flash Type	SLC	SLC	MLC	MLC
Capacity	512MB~4GB	512MB~8GB	8GB~128GB	8GB~256GB
Max. Channel	2	2	2	2
Sequential R/W (MB/sec, max.)	40/28	40/28	110/75	110/75
Max. Power Consumption	0.75W (5V x 150mA) 0.5W (3.3V x 150mA)	0.75W (5V x 150mA) 0.5W (3.3V x 150mA)	1.05W (5V x 150mA) 0.69W (3.3V x 150mA)	1.05W (5V x 150mA) 0.69W (3.3V x 150mA)
Thermal Sensor	N	N	N	N
External DRAM Buffer	N	N	N	N
ATA Security	Y	Y	Y	Y
S.M.A.R.T	Y	Y	Y	Y
Dimension (WxLxH/mm)	40-pin: 60.2 x 27.3 x 6.4 44-pin: 50.3 x 27.3 x 5.8	40-pin (A,B type): 55 x 32.4 x 12.9 40-pin (C,D type): 55 x 32.4 x 14.6 40-pin (E,F type): 55 x 32.4 x 18.3 44-pin (A,B type): 48 x 32.6 x 6.7 44-pin (C,D type): 48 x 32.6 x 12.8 44-pin (E,F type): 48 x 32.6 x 12.9	50.3 x 27.3 x 7.5	A,B type: 48 x 32.6 x 7.3
Environment	Vibration: 20G@7~2000Hz/Shock: 1500G@0.5ms/Storage Temperature: -55°C ~ +95°C/MTBF: >3 million hours			
Standard Temp. OP (0°C~+70°C)	40PIN DE0H-XXXD41AC*** 44PIN DE4H-XXXD41AC***	40PIN DE0P%-XXXD41AC*** 44PIN DE4P%-XXXD41AC***	DEE4H-XXXD53BC***	DEE4%-XXXD53BC***
Wide Temp. OP (-40°C~+85°C)	40PIN DE0H-XXXD41AW*** 44PIN DE4H-XXXD41AW***	40PIN DE0P%-XXXD41AW*** 44PIN DE4P%-XXXD41AW***	DEE4H-XXXD53BW***	DEE4%-XXXD53BW***
Note	xxx = density (512MB=512, 01GB=01G, 02GB=02G, 04GB=04G, 08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G, 128GB=A2, 256GB=B56) ***= flash configuration (internal control code), %=Horizonyal type(A,B,C,D,E,F)			

Mini PCIeDOM

The Innodisk Mini PCIeDOM is a flash-based disk module with standard Mini PCIe form factor, and PCIe Gen1 interface. It supports multiple operating systems with no driver needed, including Windows XP, Windows 7, and Windows 10, as well as Linux-based operating systems.

Model Name	Mini PCIeDOM 1SE	Mini PCIeDOM 1ME3
Key Features	1. Standard Mini PCIe form factor 2. Driver-less 3. PCIe Gen1x1	1. Standard Mini PCIe form factor 2. Driver-less 3. PCIe Gen1x1
Interface	PCIe Gen1x1	PCIe Gen1x1
Flash Type	SLC	MLC
Capacity	4GB~64GB	16GB~256GB
Max. Channel	4	2
Sequential R/W (MB/sec, max.)	85/85	130/100
Max. Power Consumption	2.3 W (3.3V x 700mA)	2 W (3.3V x 620mA)
Thermal Sensor	STD : N, W/T : Y	
External DRAM Buffer	N	N
iData Guard	Y	Y
iCell	N	N
TRIM	N	N
ATA Security	Y	Y
S.M.A.R.T	Y	Y
Dimension (WxLxH/mm)	30.0 x 50.95 x 5.0	30.0 x 50.9 x 5.0
Environment	Shock: 1500G@0.5ms/Storage Temperature: -55°C ~ +95°C/MTBF: >3 million hours	
Standard Temp. OP (0°C~+70°C)	DEEDM-XXXJ30AC***	DEEDM-XXXD09BC***
Wide Temp. OP (-40°C~+85°C)	DEEDM-XXXJ30AW***	DEEDM-XXXD09BW***
Note	XXX = density (02GB=02G, 04GB=04G, 08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G, 128GB=A28, 256GB=B56, 512GB=C12) ***= flash configuration (internal control code) %=Flash Type	

USB

The Innodisk industrial-grade USB series is built using SLC NAND flash and features an attractive small form factor. It provides high-capacity flash memory storage while delivering faster data transmission with high reliability. It also complies with the high-speed USB 3.0 interface and is backward compatible with USB 1.1. The Innodisk USB series has a variety of special features, from plastic and metal housing to secure mounting holes and EDC choices.

Model Name	USB Drive 3SE	USB Drive 3ME	USB Drive 2SE
Key Features	1. Metal housing to enhance ESD protection 2. 30μ" golden finger for highly reliable data transfer quality		1. Metal housing to enhance ESD protection 2. 30μ" golden finger for highly reliable data transfer quality
Interface	USB 3.0		USB 2.0
Connector	Type A		Type A
Flash Type	SLC	MLC	SLC
Capacity	4GB~32GB	8GB~64GB	512MB~16GB
Max. Channel	1	1	1
Sequential R/W (MB/sec, max.)	100/85	100/50	28/24
Max. Power Consumption	0.70W (5V x 140mA)		0.85W (5V x 170mA)
Dimension (WxLxH/mm)	16.5 x 45.8 x 7.6		16.5 x 45.8 x 7.4
Environment	Vibration: 20G@7~2000Hz/Shock: 1500G@0.5ms/Storage Temperature: -55℃ ~ +95℃/MTBF: >3 million hours		
Standard Temp. OP (0℃~+70℃)	DEUA1-XXXI61SC***	DEUA1-XXXI61BC***	DEUA1-XXXI72AC***
Wide Temp. OP (-40℃~+85℃)	DEUA1-XXXI61SW***	DEUA1-XXXI61BW***	DEUA1-XXXI72AW***
Notes	XXX = density (512MB=512, 01GB=01G, 02GB=02G, 04GB=04G, 08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G, 128GB=A28, 256GB=B56, 512GB=C12) ***= flash configuration (internal control code)		

| Model Name	USB EDC Vertical 3SE	USB EDC Vertical 3ME	USB EDC Horizontal 2SE	USB EDC Horizontal 2ME	USB EDC Vertical 2SE	USB EDC Vertical 2ME
Key Features	1. High performance with USB 3.0 interface 2. Low power consumption 3. Wear-leveling supported		1. Supported mounting hole 2. 2.0/2.54-pin pitch		1. Very low profile 2. Low power consumption	
Interface	USB 3.0		USB 2.0		USB 2.0	
Connector	Standard, 20-pin, 2.00mm		Standard 9-pin, 2.54mm Low profile 9-pin 2.00mm		Standard, 9-pin, 2.54mm	
Flash Type	SLC	MLC	SLC	MLC	SLC	MLC
Capacity	4GB~32GB	8GB~64GB	512MB~32GB	8GB~128GB	512MB~16GB	8GB~64GB
Max. Channel	1	1	1	1	1	1
Sequential R/W (MB/sec, max.)	110/85	100/50	28/24	27/18	28/24	26/18
Max. Power Consumption	0.79W (5V x 158mA)		0.85W (5V x 170mA)		0.85W (5V x 170mA)	
Dimension (WxLxH/mm)	24.0 x 22.0 x 5.0		26.6 x 36.9 x 9.6 (Pin Pitch2.54) 26.6 x 36.9 x 6.6 (Pin Pitch2.00)		15.2 x 34.1 x 6.4	
Environment	Vibration: 20G@7~2000Hz/Shock: 1500G@0.5ms/Storage Temperature: -55℃ ~ +95℃/MTBF: >3 million hours					
Standard Temp. OP (0℃~+70℃)	DEUV1-XXXI61SC***	DEUV1-XXXI61BC***	DEUH1-XXXI72AC*** DEUH2-XXXI72AC***	DEUH1-XXXI72BC*** DEUH2-XXXI72BC***	DEUV1-XXXI72AC***	DEUV1-XXXI72BC***
Wide Temp. OP (-40℃~+85℃)	DEUV1-XXXI61SW***	DEUV1-XXXI61BW***	DEUH1-XXXI72AW*** DEUH2-XXXI72AW***	DEUH1-XXXI72BW*** DEUH2-XXXI72BW***	DEUV1-XXXI72AW***	DEUV1-XXXI72BW***
Notes	XXX = density (512MB=512, 01GB=01G, 02GB=02G, 04GB=04G, 08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G, 128GB=A28, 256GB=B56,) ***= flash configuration (internal control code)					

nanoSSD

The Innodisk nanoSSD is an integrated SATA storage device. It combines Innodisk's ID106/ID108 NAND flash controller and the latest NAND flash in a JEDEC MO-276 (SATA μSSD) form factor with one single ball grid array (BGA) package, giving the nanoSSD a compact size and making it very easy to integrate. The Innodisk nanoSSD, supporting SATA III 6.0Gb/s, offers excellent data transfer rates along with lower power consumption. It is an ideal solution for any kind of limited-space application.

Features

- Integrated NAND flash controller with flash in a single chip
- Compliant with JEDEC MO-276 (SATA μSSD) specifications
- SATA III interface with BGA package
- Intelligent flash management and real-time garbage collection

Benefits of nanoSSD

- Chip type, easy to integrate without mechanical interference
- SATA interface, highly compatible with x86 systems
- Excellent data transfer rates
- Fully compliant with industrial standards
- Suitable for ultra-thin and compact systems
- Zero peripheral circuits
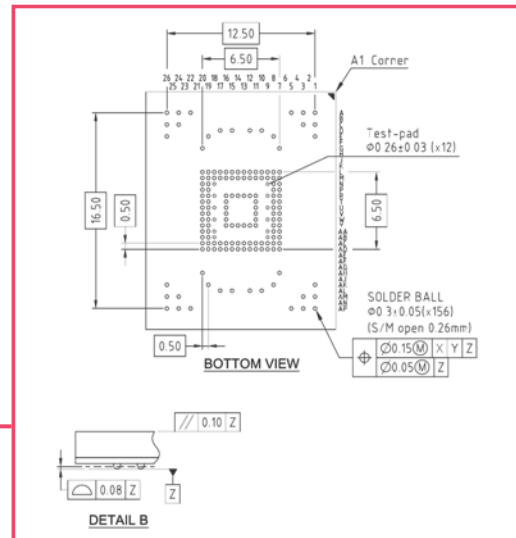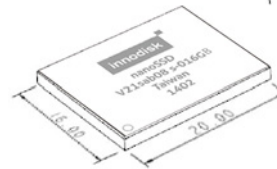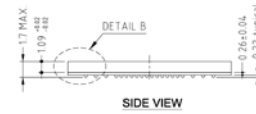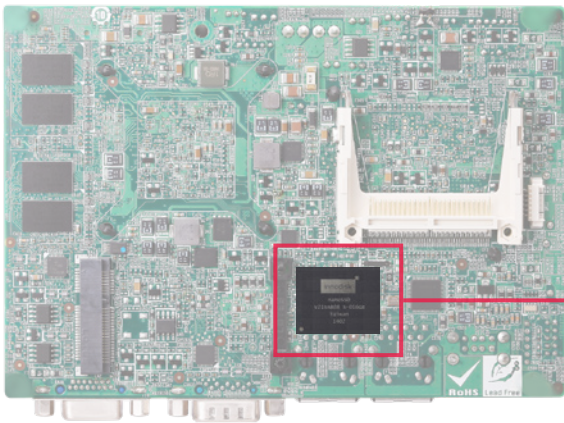
The Innodisk nanoSSD mechanical drawing

Model Name	nanoSSD 3IE3	nanoSSD 3ME3	nanoSSD SATA 3TE7
Key Features	1. Using BGA package to make controller and flash into a single chip 2. Excellent compatibility thanks to its SATA III interface 3. Compliant with JEDEC MO-276 SPEC		
Interface	SATA III 6.0Gb/s		
Flash Type	iSLC	MLC	TLC
Capacity	16GB~64GB	16GB~128GB	32GB~256GB
Max. Channel	4		
Sequential R/W (MB/sec, max.)	440/260	410/140	540 / 260
Max. Power Consumption	2.3W		2.0W
Thermal Sensor	N		Y
External DRAM Buffer	N		N
iData Guard	Y		N
iCell	N		N
TRIM	Y		Y
ATA Security	Y		Y
S.M.A.R.T	Y		Y
Dimension (WxLxH/mm)	16.0 x 20.0 x 1.7		
Environment	Shock: 1500G@0.5ms/Storage Temperature: -55°C ~ +95°C/MTBF: >3 million hours		
Standard Temp. OP (0°C~+70°C)	DENSD-XXXD06SC***	DHNSD-XXXD08BC***	DENSD-XXXDDK1BC***
Wide Temp. OP (-40°C~+85°C)	DENSD-XXXD06SW***	DHNSD-XXXD08BW***	NA
Note	xxx = density (02GB=02G, 04GB=04G, 08GB=08G, 16GB=16G, 32GB=32G, 64GB=64G, 128GB=A28) ***= flash configuration (internal control code)		

Headquarters

Innodisk Corporation

5F., No. 237, Sec. 1, Datong Rd., Xizhi Dist.,
New Taipei City, 221, Taiwan

T   +886-2-7703-3000

F   +886-2-7703-3555

E   sales@innodisk.com

Branch Offices

Japan

2F., 1-1-14, Nihonbashi-Ningyocho,
Chuo-ku, Tokyo, 103-0013 Japan

T   +81-3-6667-0161

F   +81-3-6667-0162

E   jpsales@innodisk.com

Europe

Pisanostraat 57, 5623 CB,
Eindhoven, The Netherlands

T   +31-(0)40 3045 400

F   +31-(0)40 3045 419

E   eusales@innodisk.com

USA

42996 Osgood Road
Fremont, CA 94539

T   +1-510-770-9421

F   +1-510-770-9424

E   usasales@innodisk.com

9 Timber Lane, Marlboro, NJ 07746

T +1-732-8530455

F +1-732-7846401

1 Chisholm Trail Road
Suite 4150
Round Rock, TX 78681

T +1-512-828-7464

China

807, 8 Floor, Building B, Hengyue
Center, Dengliang Road, Nanshan
District, Shenzhen, China

T   +86-0755-2167-3689
      +86-0755-2167-3690

F   +86-0755-2167-3691

E   sales_cn@innodisk.com

Shanghai **T** +86-021-64198038
          T +86-021-64195356
Beijing   **T** +86-010-82458120
          T +86-010-82458130
Chengdu   **T** +86-028-67197490

For more warranty details, please contact the Innodisk Sales Department or visit our website:
www.innodisk.com